

TO-1608BC-PG

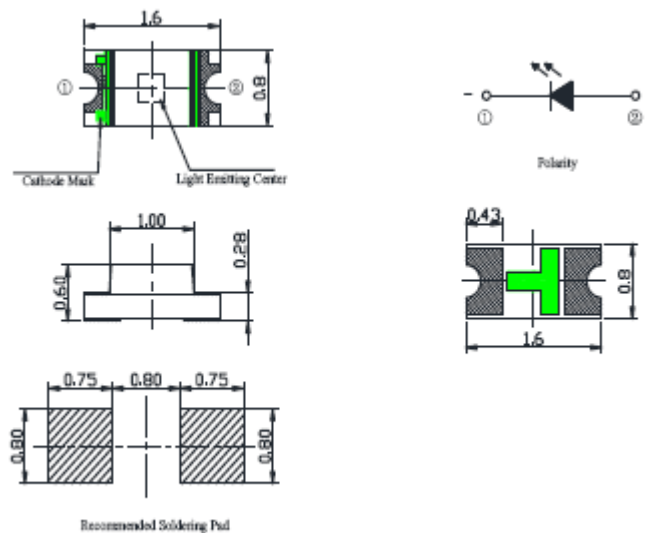
Surface Mount Device LED

Part Number	Chip		Lens Color
	Material	Source Color	
TO-1608BC-PG	InGaN	Pure Green	Water Clear

Features

- IC compatible
- Compatible with automatic placement equipment
- Compatible with infrared and vapor phase reflow soldering process
- Top view type
- Pack in 8 mm tape on 7" diameter reel
- RoHS compliant
- Moisture sensitivity Level: level 3

Dimensions



Notes:

1. All dimensions are in millimeter.
2. Tolerance is ± 0.1 mm unless individual mark noted.

Absolute Maximum Rating @ Ta=25°C

Parameter	Maximum Rating	Unit
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	80	mA
Power Dissipation	105	mW
Continuous Forward Current	25	mA
Reverse Voltage	5	V
Operating Temperature Range	-55°C to +85°C	
Storage Temperature Range	-55°C to +105°C	
IR Reflow Soldering Profile For Lead Free Soldering	260°C	

Electrical / Optical Characteristic @ Ta=25°C

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	I _v	417		917	mcd	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA
Forward Voltage	V _F		2.9		V	I _F =20mA
Dominant Wavelength	λ _d		527		nm	I _F =20mA
Spectral Line Half-Width	Δλ		26		nm	I _F =20mA
Reverse Current	I _R			10	μA	V _R =5V

Bin Code List for Reference

Luminous Intensity		Unit : mcd@20mA
Bin Code	Min	Max
G1	417	542
G2	542	705
G3	705	917

Tolerance of Luminous Intensity on each bin is $\pm 15\%$

Dominant Wavelength		Unit : nm@20mA
Bin Code	Min	Max
524526	524	526
526528	526	528
528530	528	530
530532	530	532

Tolerance of Dominant Wavelength on each bin is $\pm 1\text{nm}$

Forward Voltage		Unit : nm@20mA
Bin Code	Min	Max
V0	2.6	2.8
V1	2.8	3.0
V2	3.0	3.2
V3	3.2	3.4

Tolerance for each Forward Voltage Bin is $\pm 0.1\text{V}$